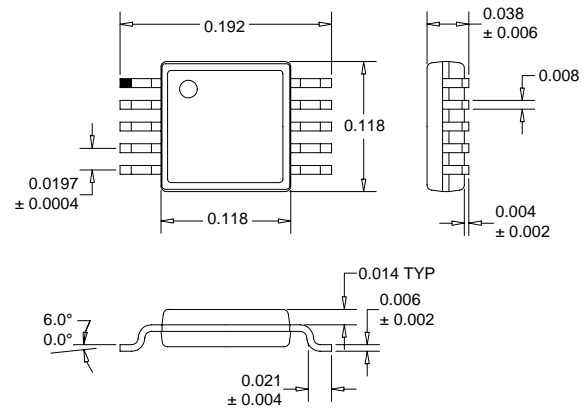


### Typical Applications

- UHF Digital and Analog Receivers
- Digital Communication Systems
- Spread-Spectrum Communication Systems
- Commercial and Consumer Systems
- Portable Battery-Powered Equipment
- General Purpose Frequency Conversion

### Product Description

The RF2495 is a front-end receiver IC chip developed for the handset/portable battery-powered equipment markets. The chip contains an RF 15dB attenuator, an LNA and a passive mixer. By using a state-of-the-art Silicon Bi-CMOS process, the LNA has high dynamic range under low DC operating conditions and the passive mixer requires no DC bias at all. Packaged in the industry-standard MSOP-10 package, the device is well-suited for limited board space applications.



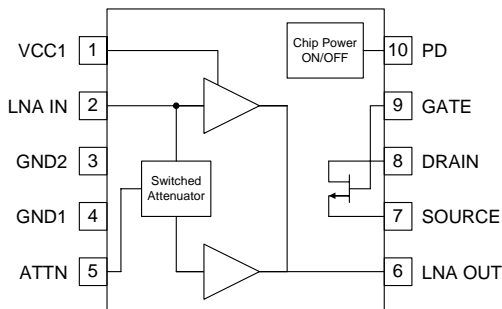
### Optimum Technology Matching® Applied

- |                                     |                                   |                                                  |
|-------------------------------------|-----------------------------------|--------------------------------------------------|
| <input type="checkbox"/> Si BJT     | <input type="checkbox"/> GaAs HBT | <input type="checkbox"/> GaAs MESFET             |
| <input type="checkbox"/> Si Bi-CMOS | <input type="checkbox"/> SiGe HBT | <input type="checkbox"/> Si CMOS                 |
| <input type="checkbox"/> InGaP/HBT  | <input type="checkbox"/> GaN HEMT | <input checked="" type="checkbox"/> SiGe Bi-CMOS |

Package Style: MSOP-10

### Features

- Single Supply 3V Operation
- 1.9dB LNA NF
- 0dBm Input IP3
- Small MSOP-10 Package
- Low Current Drain (11 mA maximum)
- Very Low Cost



Functional Block Diagram

### Ordering Information

RF2495                      900MHz 3V Low Current LNA/Mixer  
 RF2495 PCBA            Fully Assembled Evaluation Board

RF Micro Devices, Inc.  
 7628 Thorndike Road  
 Greensboro, NC 27409, USA

Tel (336) 664 1233  
 Fax (336) 664 0454  
<http://www.rfmd.com>

# RF2495

## Absolute Maximum Ratings

Parameter	Rating	Unit
Supply Voltage	-0.5 to +3.6	V <sub>DC</sub>
Input RF Level	+10	dBm
Operating Ambient Temperature	-40 to +85	°C
Storage Temperature	-40 to +150	°C



Caution! ESD sensitive device.

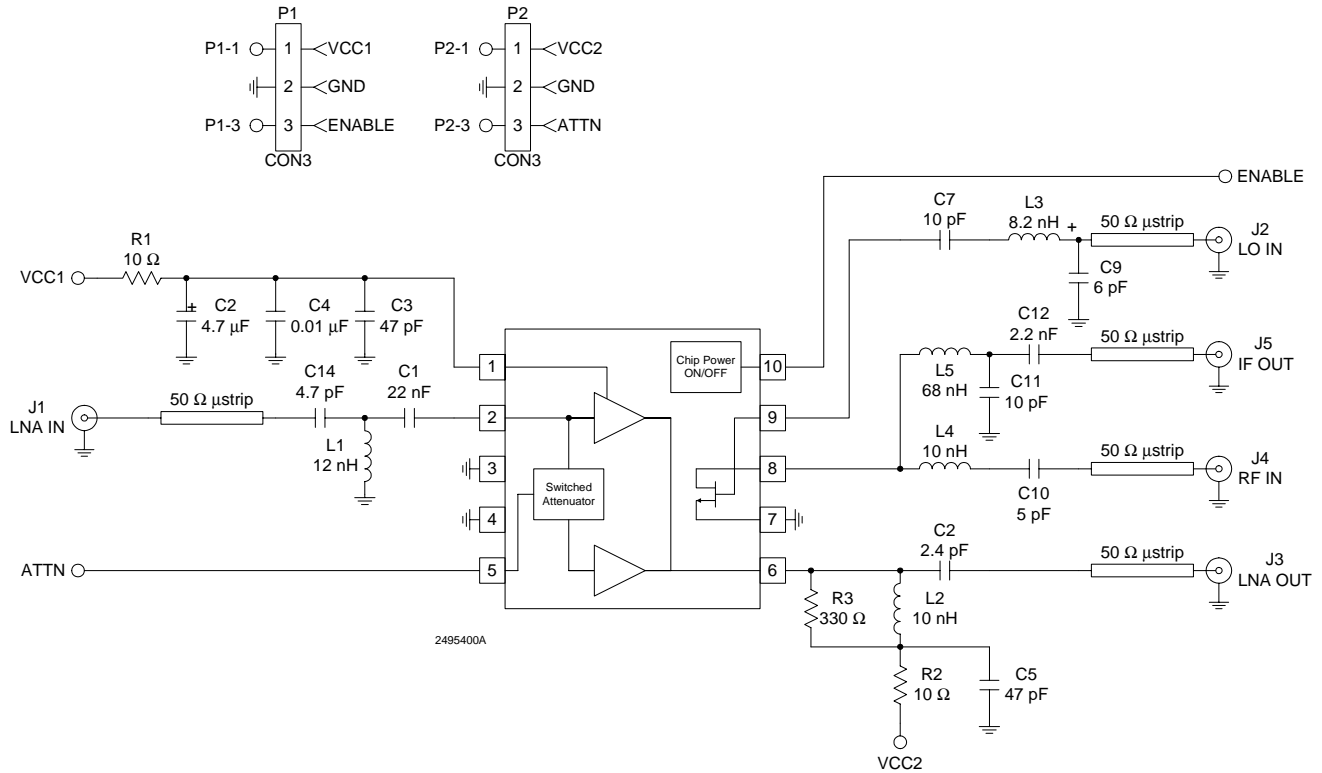
RF Micro Devices believes the furnished information is correct and accurate at the time of this printing. However, RF Micro Devices reserves the right to make changes to its products without notice. RF Micro Devices does not assume responsibility for the use of the described product(s).

Parameter	Specification			Unit	Condition
	Min.	Typ.	Max.		
<b>Overall</b> RF/LO Frequency Range		850 to 940 800 to 1000		MHz MHz	T=25°C, V <sub>CC</sub> =3.0V Specifications Usable range
<b>LNA</b> Gain	15.5 1.0	17.0 4.0		dB dB	High gain state Low gain state
Input IP3	-2.5 +11.0	+1.0 +12.5		dBm dBm	High gain state, RF IN=-25dBm Low gain state, RF IN=-15dBm
Noise Figure		1.9 13.5	2.2	dB dB	High gain state Low gain state
Input VSWR Output VSWR			1.67:1 1.67:1		
<b>Mixer</b> Conversion Gain	-6.5 -6.0	-5.5 -5.5		dB dB	With LO=+2dBm With LO=+4dBm
Input IP3	+7.5 +10.0	+11.0 +13.0		dBm dBm	With LO=+2dBm With LO=+4dBm
LO Input Level	-2	4.0		dBm	
<b>Attenuation</b> ATTN Enable	V <sub>CC</sub> -0.3	>1.6		V	Low gain state
ATTN Disable		0	0.3	V	High gain state
<b>Power Down</b> Chip Enable	V <sub>CC</sub> -0.3	>1.6		V	Voltage applied to PD pin
Chip Disable		0		V	Voltage applied to PD pin
<b>Power Supply</b> Voltage		3.0 2.7 to 3.3		V V	Specifications Operating limits
Current Consumption		10 <1	12 3.0	mA uA	Chip enabled Chip disabled

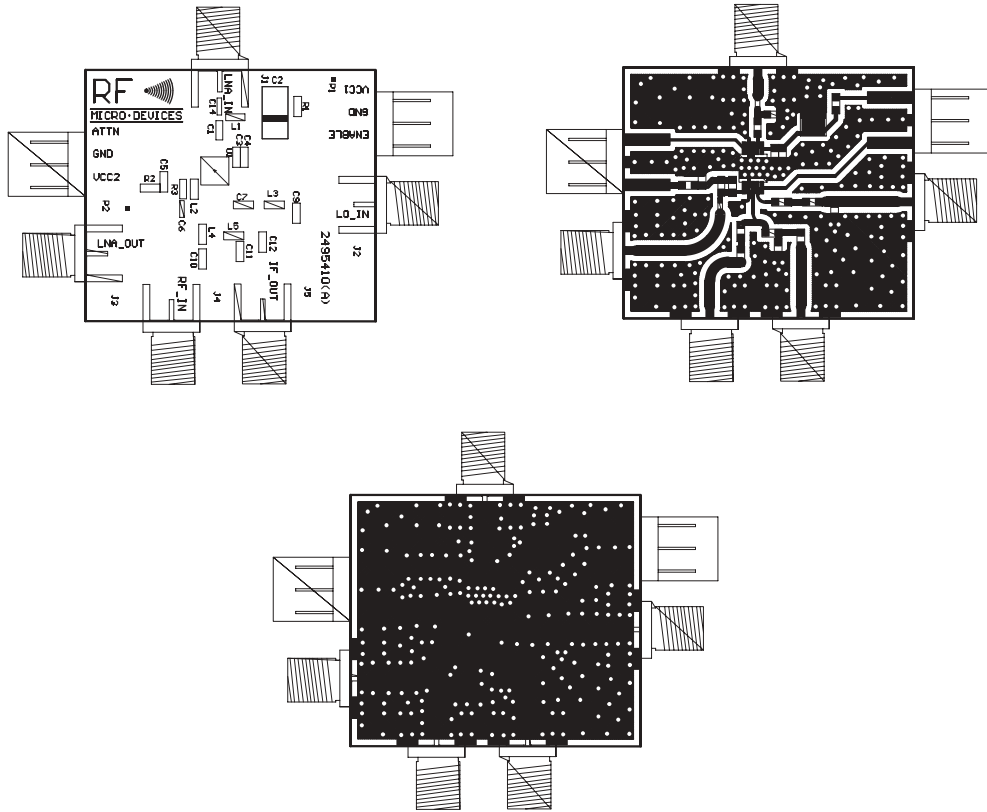
Pin	Function	Description	Interface Schematic
1	VCC1	Supply voltage for the LNA, bias circuits, and control logic. External RF bypassing is required. The trace length between the pin and the bypass capacitors should be minimized. The ground side of the bypass capacitors should connect immediately to ground plane.	
2	LNA_IN	RF Input pin. This pin is internally matched for optimum noise figure from a 50Ω source. This pin is internally DC-biased and, if connected to a device with DC present, should be blocked with a capacitor suitable for the frequency of operation.	
3	GND2	Ground connection. For best performance, keep traces physically short and connect immediately to ground plane.	
4	GND1	Ground connection for the LNA circuits. For best performance, keep traces physically short and connect immediately to ground plane.	See pin 2.
5	ATTN	Attenuation pin. A logic high reduces LNA gain by 15dB.	
6	LNA_OUT	LNA Output pin. This pin requires a connection to V <sub>CC</sub> through an inductor.	
7	SOURCE	Connection to source of MOSFET transistor used as mixer. Drain and source are symmetric.	
8	DRAIN	Connection to drain of MOSFET transistor used as mixer.	See pin 7.
9	GATE	Connection to gate of MOSFET transistor used as mixer. Internally DC-biased. Use DC-blocking capacitor.	See pin 7.
10	PD	Power control. A logic "low" turns the part off. A logic "high" (>1.6V) turns the part on.	
	ESD	This diode structure is used to provide electrostatic discharge protection to 3kV using the Human body model. The following pins are protected: 1, 3, 5, 9, 10.	

# RF2495

## Evaluation Board Schematic (Download [Bill of Materials](http://www.rfmd.com) from [www.rfmd.com](http://www.rfmd.com).)

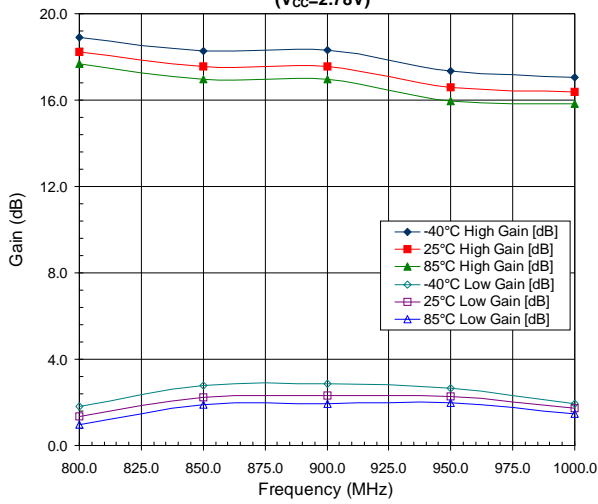


Evaluation Board Layout  
Board Size 1.108" x 1.281"  
Board Thickness 0.031", Board Material FR-4

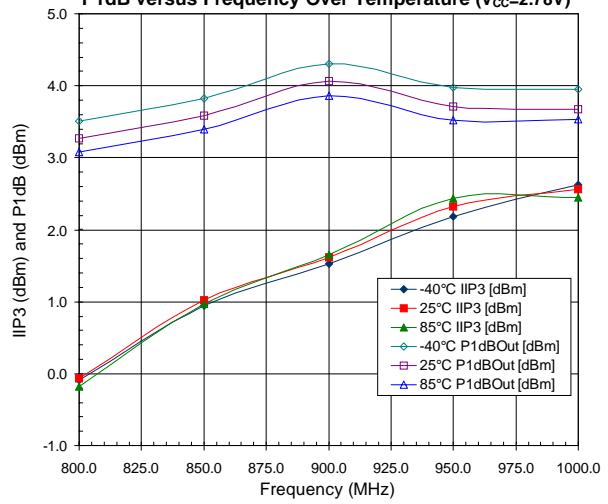


# RF2495

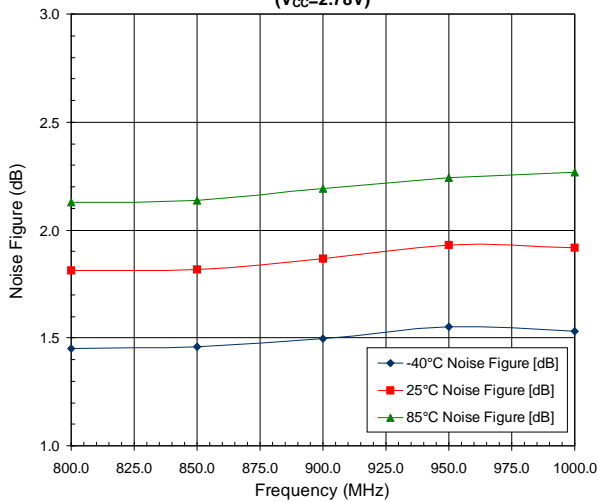
**LNA: Gain versus Frequency Over Temperature**  
(V<sub>CC</sub>=2.78V)



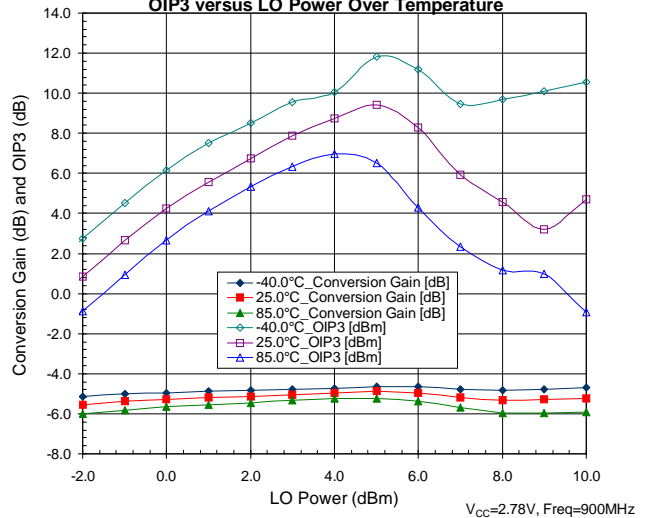
**LNA: IIP3 versus Frequency and P1dB versus Frequency Over Temperature (V<sub>CC</sub>=2.78V)**



**LNA: Noise Figure versus Frequency Over Temperature**  
(V<sub>CC</sub>=2.78V)



**Mixer: Conversion Gain versus LO Power, OIP3 versus LO Power Over Temperature**



**Mixer: Conversion Gain versus Frequency, OIP3 versus Frequency Over Temperature**

